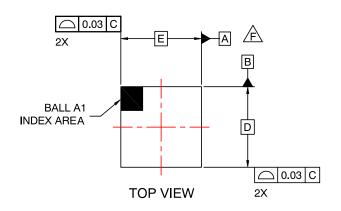
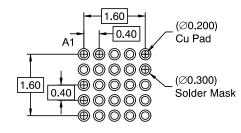


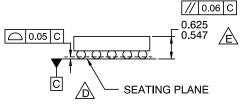
WLCSP25 2.4x2.0x0.586 CASE 567SQ ISSUE O

DATE 30 NOV 2016

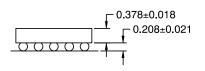


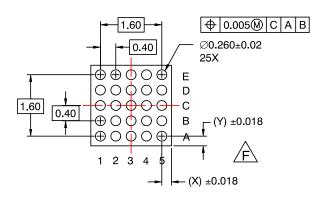


RECOMMENDED LAND PATTERN (NSMD PAD TYPE)



SIDE VIEWS





BOTTOM VIEW

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASMEY14.5M, 1994.
- DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).
- FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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DESCRIPTION:	WLCSP25 2.4x2.0x0.586		PAGE 1 OF 1

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